

Preliminary Programme

WORKSHOP

„ADVANCE TOPICS IN ELECTRONIC ASSEMBLING TECHNOLOGY”

April 25, 2013

- 13.00–14.15 *Registration*
- 14.15-14.30 **Welcome**
Prof. Carmen Gerigan, “Transilvania” University of Braşov,
Prof. Paul Svasta, Politehnica University of Bucharest
- 14.30-16.30 ***First Session: PCB Design***

Session chair: Prof. Zsolt Illyefalvi-Vitéz, Electronic Technology Department, Budapest University of Technology
- 14.30-15.50 **PCB Design Behind EMC Thinking**

Lorand Foelkel, M. Eng. Würth Elektronik
- 15.50-16.30 **Design and Measurement of Integrated Passive Devices and Flexible Substrate**
Detlef Bonfert, PhD, EMFT Munich, Germany
- 16.30-17.00 ***Networking Break***
- 17.00-19.00 ***Second Session: Assembling Technology***

Session chair Prof. Dan Pitică, Technical University of Cluj Napoca
- 17.00-17.30 **”Selection/Supplying of Electronic Components an Important Step for Electronic Modules Manufacturing.”**

Wojtek Kuczyński Transfer Multisort Elektronik, Poland
- 17.30-18.30 **Stencil Manufacturing Technologies and Stencil Design Guidelines**

Oliver Krammer, Ph.D., Electronic Technology Department, Budapest University of Technology
- 18.30-19.00 **Smart electronic devices in Household Appliance,**

Dominik Beier – Team Leader, Development Department – Miele Electronics